



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



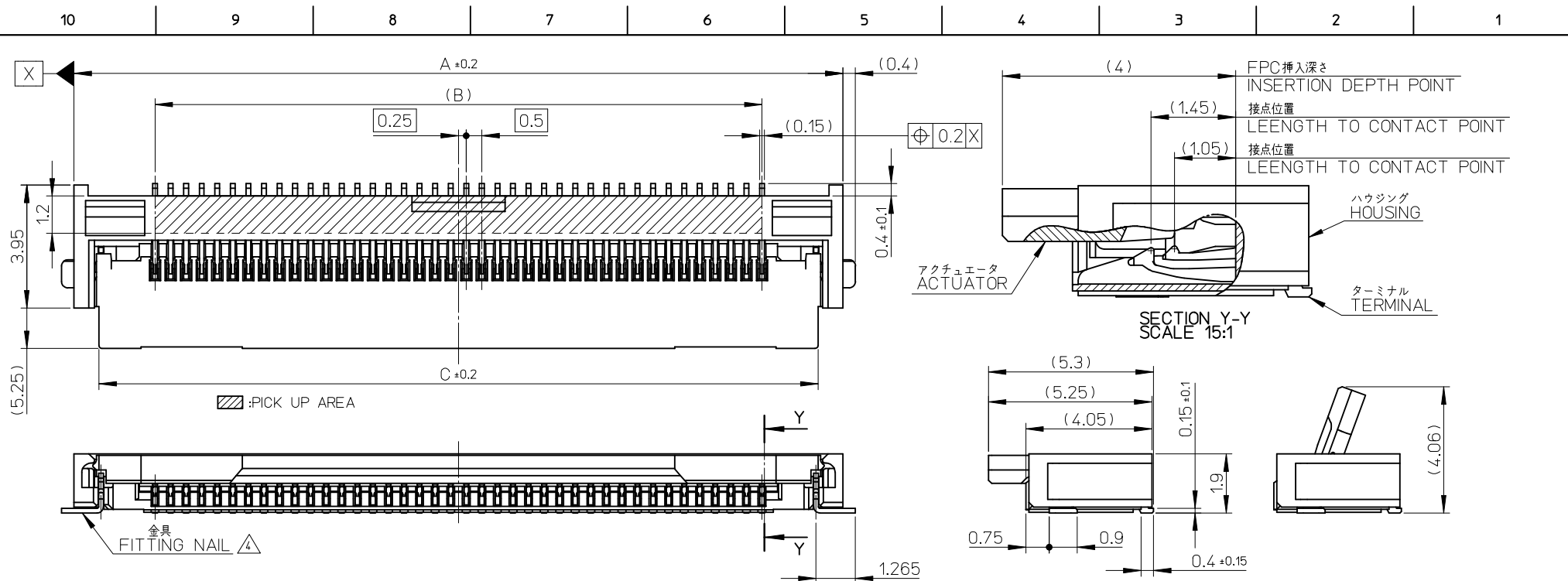
## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





注記 NOTES

1. 使用材料 MATERIAL

- ハウジング : 液晶ポリマー ガラス充填, UL94V-0(ベージュ)  
 HOUSING LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0(BEIGE)
- アクチュエータ : ポリアミド ガラス充填, UL94V-0(黒)  
 ACTUATOR POLYAMIDE GLASS FILLED, UL94V-0(BLACK)
- ターミナル : リン青銅(t=0.15)  
 TERMINAL PHOSPHOR BRONZE
- 金具 : リン青銅(t=0.15)  
 FITTING NAIL PHOSPHOR BRONZE

2. めっき仕様 PLATING

- ターミナル TERMINAL  
 コントクト部: 部分金めっき (0.05 μm以上)  
 テール部: 部分金めっき  
 下地: ニッケルめっき (1.0 μm以上)

CONTACT AREA : SEPARATED GOLD PLATING (0.05 MICROMETER MIN.)  
 SOLDER TAIL AREA : SEPARATED GOLD PLATING  
 UNDERPLATE : NICKEL OVERALL (1.0 MICROMETER MIN.)

金具 FITTING NAIL

- 鍍めつき (1.0 μm以上)  
 下地: ニッケルめっき (1.0 μm以上)  
 TIN PLATING (1.0 MICROMETER MIN.)  
 UNDER PLATING : NICKEL PLATING (1.0 MICROMETER MIN.)

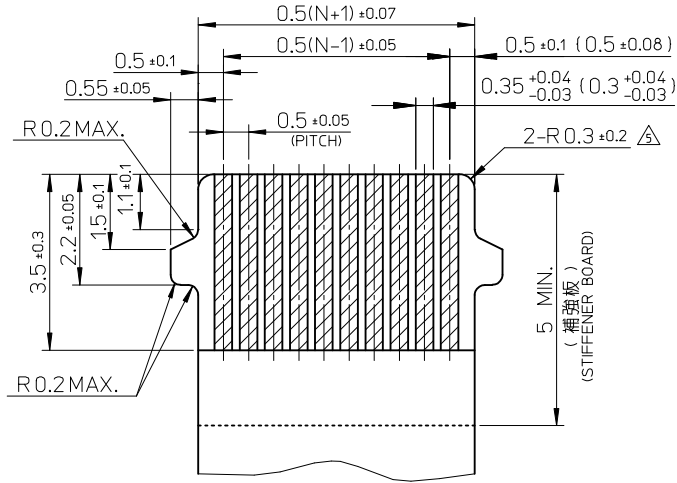
3. エンボステープ梱包時は、アクチュエータが閉じた状態とする。  
 IN THE PACKAGE, ACTUATOR OF PART SHOULD BE CLOSED.

△ パターン剥離止め用金具  
 FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

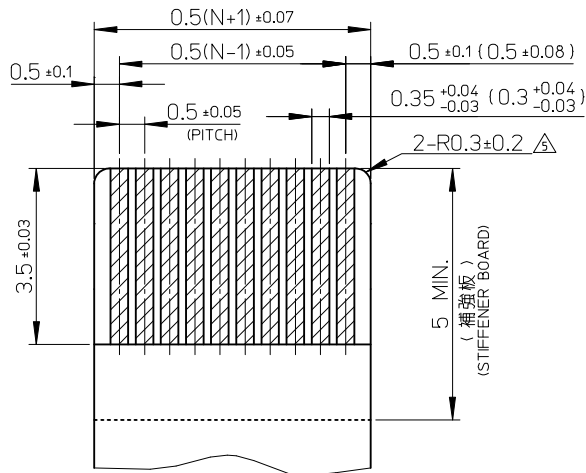
△ R0.3は、FPC導体部にかからないこと。  
 R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

6. N: 極数 N: CIRCUIT.  
 7. ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT  
 8. テールと金具を併せた平坦度は0.1mm以下とする。  
 TAILS AND NAILS COPLANALITY TO BE 0.1mm MAX.

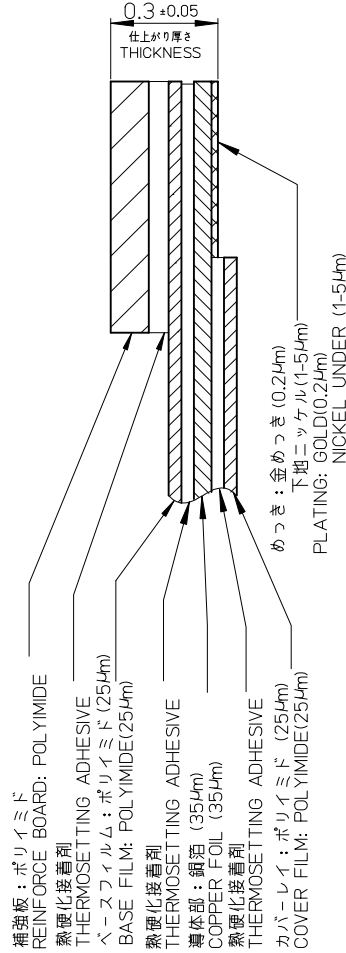
REVISED EC NO: J2017-0308 DRWN: JASANUMA 2016/12/06 CHKD: YOBAYASHI 2016/12/06 APPR: TKUSUHARA01 2016/12/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 8:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±0.03	DRAWN BY DATE		TITLE		
	0.25 OVER 0.5 UNDER	±0.05	JASANUMA 2014/02/25		0.5 FPC CONN ZIF E/O 2 CONTACTS TYPE HSG ASSY (H=1.9)		
	0.5 OVER 1.0 UNDER	±0.1	CHECKED BY DATE		molex		
1.0 OVER 10 UNDER	±0.2	KTAKAHASHI 2014/07/28		APPROVED BY DATE		DOCUMENT NO.	SHEET NO.
10 OVER 30 UNDER	±0.25	YNOGAWA 2014/11/10		MATERIAL NO.		SD-505110-001	1 OF 3
30 OVER	±0.3	SEE SHEET 3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					



適合FPC/FFC推奨寸法  
 APPLICABLE FPC/FFC  
 RECOMMENDED DIMENSION  
 ( ): FFCに適用  
 ( ): APPLY TO FFC



耳無し適合FPC/FFC推奨寸法  
 APPLICABLE NON-TAB FPC/FFC  
 RECOMMENDED DIMENSION  
 ( ): FFCに適用  
 ( ): APPLY TO FFC



FPC構成推奨仕様  
 STRUCTURE OF FPC

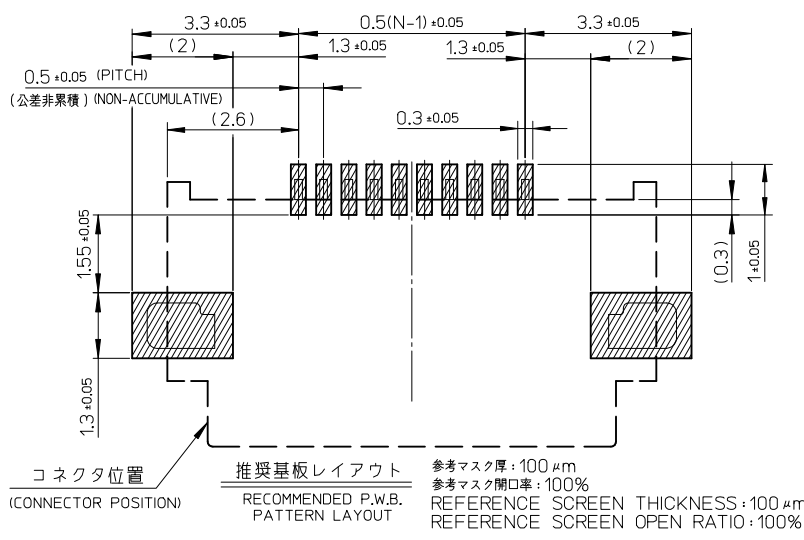
### FPC/FFCについて ABOUT FPC/FFC

打ち抜き方向は導体側から補強板側を推奨します。  
 導体部については軟箔銅35μmまたは50μmを推奨します。  
 FFCに規定された定格温度がFFC単体前提である場合が御座います。  
 コネクタと組み合わせての実用に置いて、接着層が劣化するなどの信頼性を満足できないケースを回避するため、  
 実機での評価/確認をお願い致します。  
 RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE  
 RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL  
 RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER  
 NOTE: WHEN ACTUALLY USING IT WITH CONNECTOR, PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH AN ACTUAL EQUIPMENT TO EVADE THE CASE WHERE RELIABILITY CANNOT BE FILLED (THE ADHESIVE LINE OF FFC IS DETERIORATED ETC.)

### FPCについて ABOUT FPC

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。  
 接着剤は熱硬化接着剤を推奨します。  
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。  
 RECOMMENDED MATERIAL/THICKNESS.  
 RECOMMENDED STIFFENER MATERIAL: POLYIMIDE  
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER  
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE  
 NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY. THERE IS A POSSIBILITY THAT THE PRESCRIPT TEMPERATURE OF FFC IS SET TO SINGLE IT.

SEE SHEET 1 EC NO: J2017-0308 DRWN: JASANUMA 2016/12/06 CHKD: YKOBAYASHI 02/2016/12/06 APPR: TKUJHARA01 2016/12/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER 0.5 UNDER	±0.05	JASANUMA	2014/02/25	0.5 FPC CONN ZIF E/O 2 CONTACTS TYPE HSG ASSY (H=1.9)		
	0.5 OVER 1.0 UNDER	±0.1	CHECKED BY	DATE	molex		
1.0 OVER 10 UNDER	±0.2	KTAKAHASHI	2014/07/28	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.
10 OVER 30 UNDER	±0.25	YNOGAWA	2014/11/10	SEE SHEET 3		SD-505110-001	SHEET NO. 2 OF 3
30 OVER	±0.3	ANGULAR ±1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3			



43.1	39.5	44.7	505110-8091	80
38.1	34.5	39.7	505110-7091	70
37.1	33.5	38.7	505110-6891	68
35.1	31.5	36.7	505110-6491	64
33.1	29.5	34.7	505110-6091	60
28.1	24.5	29.7	505110-5091	50
25.6	22.0	27.2	505110-4591	45
23.1	19.5	24.7	505110-4091	40
20.6	17	22.2	505110-3591	35
18.1	14.5	19.7	505110-3091	30
17.1	13.5	18.7	505110-2891	28
16.1	12.5	17.7	505110-2691	26
15.1	11.5	16.7	505110-2491	24
14.1	10.5	15.7	505110-2291	22
13.1	9.5	14.7	505110-2091	20

CONNECTOR SERIES NO. 505110-\*\*11

C B A EMBOSSED PACKAGE  
オーダー番号 ORDER NO. Ckt

SEE SHEET 1 EC NO: J2017-0308 DRWN: JASANUMA 2016/12/06 CHKD: YKOBAYASHI 2016/12/06 APPR: IKUSUHARA01 2016/12/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	± 0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER 0.5 UNDER	± 0.05	JASANUMA	2014/02/25	0.5 FPC CONN ZIF E/O 2 CONTACTS TYPE HSG ASSY (H=1.9)		
	0.5 OVER 1.0 UNDER	± 0.1	CHECKED BY	DATE	<b>molex</b> DOCUMENT NO. SD-505110-001 SHEET NO. 3 OF 3		
	1.0 OVER 30 UNDER	± 0.2	KTAKAHASHI	2014/07/28			
10 OVER 30 UNDER	± 0.25	APPROVED BY	DATE	SEE CHART			
30 OVER	± 0.3	YNOGAWA	2014/11/10	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
ANGULAR ±1 °		MATERIAL NO.					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					